



LAMC 2023 Call for Papers

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The fourth edition of LAMC will take place in San Jose, Costa Rica, on December 6-8, 2023. After three successful editions in Puerto Vallarta, Mexico (2016), Arequipa, Peru (2018), and Cali, Colombia (2021, virtual), LAMC returns fully presential to San Jose as a high-quality technical forum for the Latin America Region and all the MTT-S community.

San Jose, located in the central region of Costa Rica, is a strategic place nearby SJO International Airport, where principal government institutions, universities, and industry converge in a metropolitan area with over three million people. The west of this urban area hosts a vibrant business environment, with the operation of more than 300 high-tech companies in fields such as semiconductors, electronics, software, and biomedical applications, among others.

We encourage the submission of original, unpublished research focused on (but not limited to) the following topics of interest:

1. **Passive components, circuits, and devices** (planar and nonplanar components and circuits, filters and multiplexers, tunable devices, and metamaterials).
2. **Active devices, circuits, and subsystems** (RFICs & MMIC design, power amplifiers, linearization techniques, low-noise circuits, signal generation, conversion & control modules, linear and non-linear modeling and characterization).
3. **RF systems and applications** (microwave systems and front-ends industrial scientific and medical applications, navigation systems, intelligent transportation systems, imaging, sensors, wireless power transmission).
4. **Communication systems** (terrestrial, vehicular, satellite and indoor applications, wireless and cellular communication systems).
5. **Active and passive antennas** (phase arrays, integrated antennas, smart antennas, digital-beam forming and MIMO).
6. **Signal-power integrity and high-speed digital techniques** (EM interference and compatibility, high-speed interconnects, post-silicon validation techniques, power delivery networks, computer simulations and measurements).
7. **CAD techniques for RF and microwave engineering** (surrogate-based modeling and optimization, space mapping-based methods, model order reduction, machine learning approaches, statistical analysis and design, EM-based and multi-physics design optimization, EM field theory, time- and frequency-domain numerical techniques).

Papers submitted to LAMC 2023 will be peer reviewed and evaluated based on originality, quantitative content, clarity, and interest to the audience. The review process will be single-blind. LAMC will use EDAS as the electronic paper management system. All accepted and presented papers will be published in the LAMC Conference Proceedings and submitted for inclusion in the *IEEE Xplore Digital Library*.

English will be the official language of the conference. Prospective authors are cordially invited to submit a three-page two-column manuscript, following the instructions available at the conference website, (<https://lamc-ieee.org>).

Important Dates:

Proposals for special sessions and tutorials:	July 10, 2023
Submission regular papers:	July 24, 2023
Notification of acceptance:	September 1, 2023
Camera-ready submission:	October 1, 2023
Author registration deadline:	October 15, 2023